

SMD Power Resistors

Specifications



Type			RWN 5020		RWC 5020			
Styles			5020					
Dimensions			mm		non inductive, no winding		wirewound on ceramic	
Power rating $\vartheta_0 = 200^{\circ}\text{C}$			W		P_{25} 2,2 P_{40} 2,0 P_{70} 1,6			
Single pulse			$I_{\text{max.}}$ A $E_{\text{i, max}}$ mWs $T_{\text{imp, max}}$ ms		50 625 5			
periodic pulse load			i_{max} A		30 (R003 .. .R018) 40 (R022 ... R050)			
			$E_{\text{i,per, max}}$ mWs $t_{\text{imp, max}}$ ms t_{pause} ms		225 5 100			
Tolerance			%		1, 2, 5 (F, G, J)		1, 2, 5 (F, G, J)	
Resistance range			Ω		0R002 ... 0R050		0R01 ... 220R	
Temperature coefficient			ppm K ⁻¹		see diagram		± 80	
E-Series					0R003, 0R005, $\geq 0R01$: E 12		E 12	
					diverging values on request			
max. cont. work. voltage			V_{RMS}		$\sqrt{P \cdot R}$			
Thermal resistance			K/W		100 ¹⁾			
Insulation voltage (1 min.)			V_{RMS}		1000			
Insulation resistance					> 1000M Ω			
Climatic category					55/175/56			
Temperature range			$^{\circ}\text{C}$		−55 . . . 200			
Endurance (P_{70} , 70°C, 1000h)			$\left[\frac{\Delta R}{R}\right] \%$		$\leq 1,0$			
Damp heat, steady state			$\left[\frac{\Delta R}{R}\right] \%$		$\leq 0,25$			
Resistance to soldering heat			$\left[\frac{\Delta R}{R}\right] \%$		$\leq 0,25$			
Short time overload (5 * P_{70} /5sec)			$\left[\frac{\Delta R}{R}\right] \%$		$\leq 1\%$			
Temperature shock					$\leq 0,25$			
Board-bending-test					no interruption			
Solderability					suitble for wave and reflow soldering in acc. with CECC 0082			

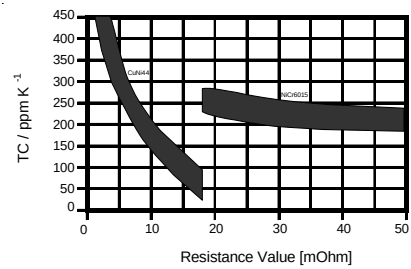
¹⁾ Thermal data according to DIN 44050 with solder pads as on next page.

Temperature Coefficient :

Range (RWC 5020):

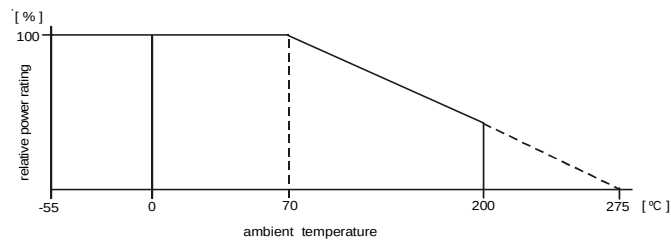
$\geq 0R01$	$\leq 0R024$	$400 \pm 50 \text{ ppm/K}$
$\geq 0R027$	$\leq 0R091$	appr. $+180 \text{ ppm/K}$
$\geq 0R1$	$\leq 15R$	$0 \pm 20 \text{ ppm/K}$
$\geq 16R$	$\leq 220R$	$0 \pm 10 \text{ ppm/K}$

Diagram (RWN 5020):

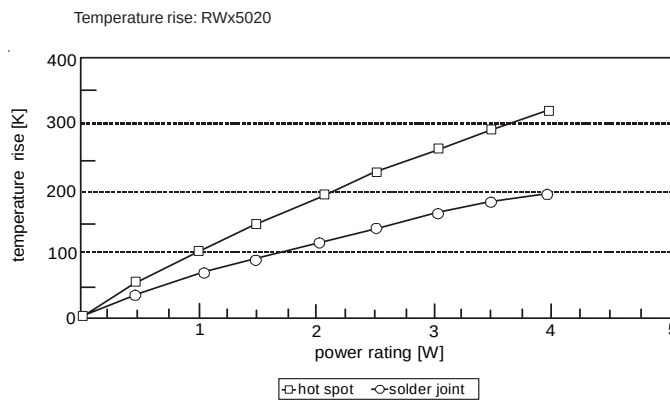


Temperature range $-55 +200^{\circ}\text{C}$

Derating:



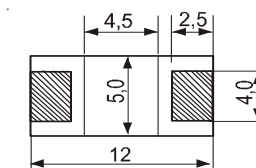
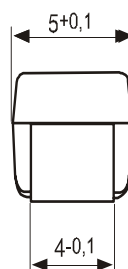
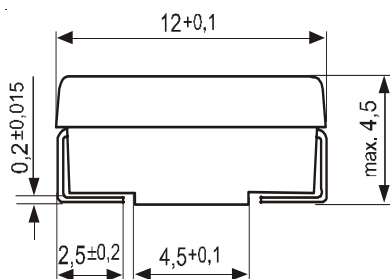
Temperature rise:



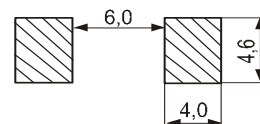
Part mounted on FR 4, pads as recommended, copper layer $35 \mu\text{m}$

recommended solder pads:

Dimensions:



Bottom view



Solder pads

Marking:

Resistor: printed in clear: Type - Value - Tolerance

Packaging

additional Batch-No. - Production date

Packaging:

blisertape 24 mm antistatic / 1500 pcs. on reel 330 mm Ø

Ordering example:

RWC 5020 F K - 13 1R
Type tolerance blister tape reel TC reel diameter R-value

SMD Power Metal film resistors

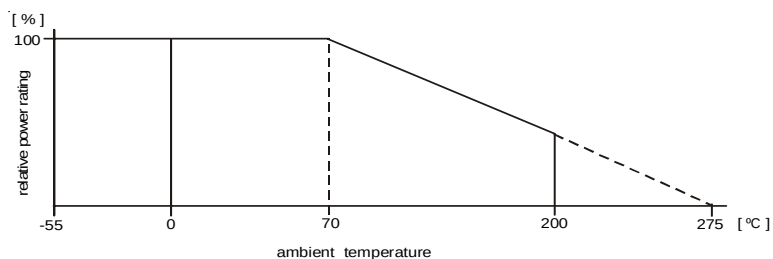


Specifications

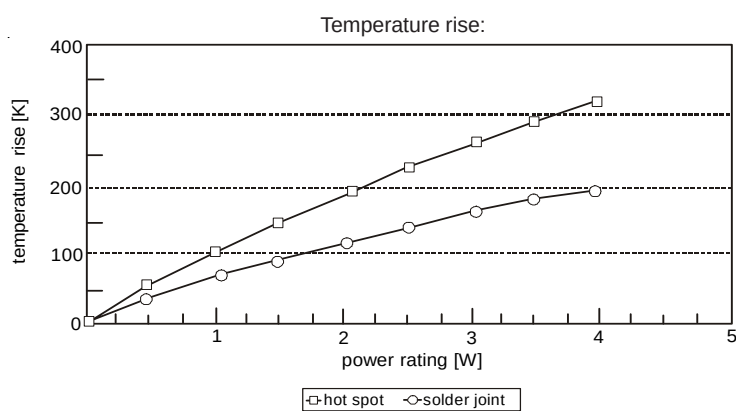
Type		RWP 5020	
Style		5020	
Power rating $\vartheta_0 = 200^\circ\text{C}$	W	P_{25} 2,2 P_{40} 2,0 P_{70} 1,6	
		higher power depends on mounting technology	
Tolerance	%	1	5
Resistance range	Ω	10R ... 1M	1R0 ... 1M
Temperature coefficient	ppm K^{-1}	± 50	± 200
E-Series		E 96	E 12 preferred
max. cont. work. voltage	V_{RMS}	500	
Thermal resistance	K/W	90 ¹⁾	
Insulation voltage (1 min.)	V_{RMS}	1000	
Insulation resistance		> 1000M Ω (dry)	
Climatic category		55/175/56	
Temperature range	$^\circ\text{C}$	-55 ... 175	
Endurance (P_{70} , 70 $^\circ\text{C}$, 1000h, intermed.)	$\left[\frac{\Delta R}{R}\right] \%$	$\leq 1,5$	
Damp heat, steady state	$\left[\frac{\Delta R}{R}\right] \%$	$\leq 1,5$	
Resistance to soldering heat	$\left[\frac{\Delta R}{R}\right] \%$	$\leq 0,25$	
Short time overload (5 * P_{70} /2sec)	$\left[\frac{\Delta R}{R}\right] \%$	$\leq 1\%$	
Temperature shock		$\leq 0,25$	
Board-bending-test		no interruption	
Solderability		suitble for wave and reflow soldering in acc. with CECC 0082	

¹⁾ Thermal data according to DIN 44050 with solder pads as on next page.

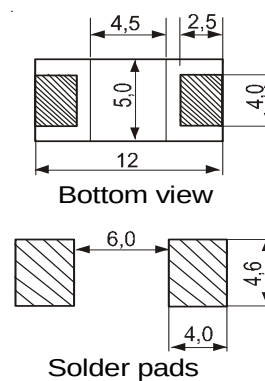
Derating:



Temperature rise:

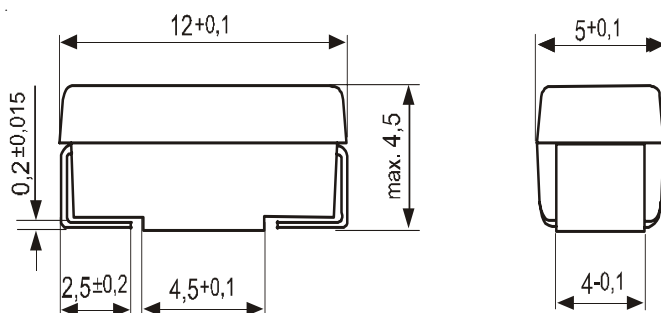


Recommended solder pads:



Part mounted on FR 4, pads as recommended, copper layer 35 µm

Dimensions in mm:



Marking:

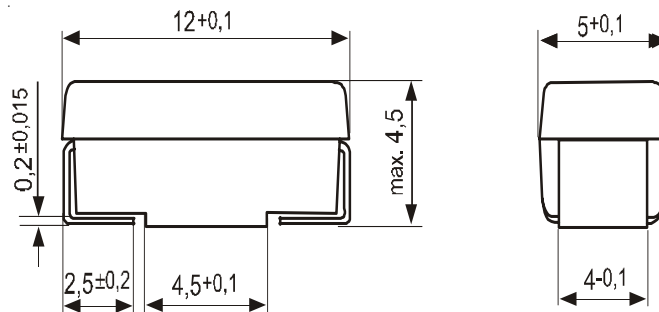
Resistor: Printed in clear: Type - Value - Tolerance
Package additional Batch-Nr. - Production date

Packaging:

Blisertape 24 mm antistatic / 1.500 pcs on reel 330 mm Ø

Ordering example:

RWP 5020	F	K	-	13	10K
Type	Tolerance	blister tape reel	TC	reel diameter	R-value

Low-Power, moulded type, RWN family:

If power rating is not the main concern, i.e. current ranges below 5A, a current sensing device in a standard resistor package may be suitable.

VITROHM offers a SMD-version (RWN), that was designed for automatic PCB-assembly with in blister-tape.

The power rating for this type is limited by the max. temperature of the moulding material. Overheating may cause carbonizing of the plastic, short circuit may occur.

This limits also the pulse handling capacity.

50A can be carried by the internal contacts, but energy must not exceed 625 mWs.